

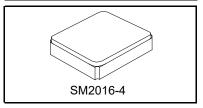


XTL2105H-1

Features:

- Surface Mount Hermetic Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Ultra Miniature Package
- Moisture Sensitivity Level (MSL): Level-1

39.000000 MHz Crystal Unit



Description and Applications:

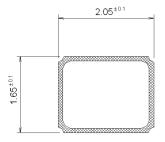
Surface mount 2.0mmx1.6mm crystal unit for use in wireless communications devices, especially for a need of ultra miniature package for mobility.

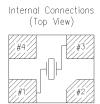
Electrical Specifications:

XTL2105H-1	Specification				
Nominal Frequency	39.000000 MHz				
Mode of Oscillation	Fundamental				
Storage Temperature Range	-40°C to +125°C				
Operating Temperature Range	-40°C to +125°C				
Frequency Stability over Operating Temperature Range	+/-35 ppm (referred to the value at 29°C)				
Frequency Slope over Temperature	2 ppm/C max @120°C (referred to the value at 29°C)				
S curve 3 order curve fitting coefficient 1	-0.13 ppm/°C typical				
S curve 3 order curve fitting coefficient 2	-12.73 e ⁴ -ppm/°C ² typical				
S curve 3 order curve fitting coefficient 3	9.92 e ⁵ -ppm/°C³ typical				
Frequency Perturbations	1.0 ppm max				
Frequency Make Tolerance (FL)	+/-8 ppm @ 25°C +/- 3°C				
Equivalent Series Resistance (ESR)	35 Ω max				
Nominal Drive Level	50uW typical and 200uW max				
Shunt Capacitance (Co)	2.0 pF max				
Load Capacitance (CL)	10 pF				

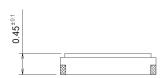
Aging	+/-3ppm/5year
Insulation Resistance	500 MΩ min./DC 100V
Marking	Laser Marking
Unit Weight	5.7mg+/-0.5mg

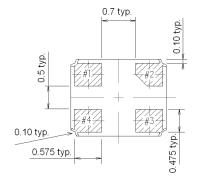
Mechanical Dimensions (mm): Base





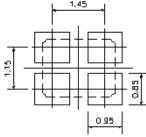
[NOTE] #2, #4 is connected with a cover





	Pin Connection
#1 pin	IN/OUT
#2 pin	GND
#3 pin	IN/OUT
#4 pin	GND

Recommended Land Pattern: (unit: mm)

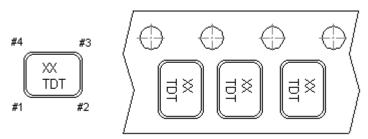


Recommended Land Pattren

Marking:

Line 1: XX; Frequency (39)

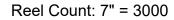
Line 2: T; Traceable Code + D; date Code of Year/Month+ T; Traceability code (1 or no letter)

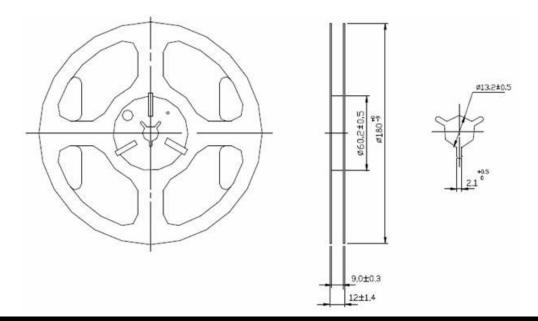


Date Code Table: Year/Month

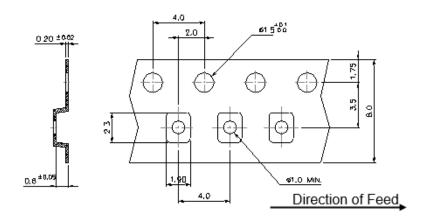
Year/Month	1	2	3	4	5	6	7	8	9	10	11	12
2018	Α	В	С	D	Е	F	G	Н	J	K	L	М
2019	N	Р	Q	R	S	Т	U	V	W	Х	Υ	Z
2020	а	b	С	d	е	f	g	h	i	j	k	m
2021	n	р	q	r	s	t	u	٧	W	х	у	Z
2022	Α	В	O	D	Е	F	G	Ι	٦	K	L	М
2023	N	Р	Q	R	S	Т	U	٧	W	Х	Υ	Z
2024	а	b	С	d	е	f	g	h	i	j	k	m
2025	n	р	q	r	ø	t	а	٧	W	х	у	Z
2026	Α	В	С	D	Е	F	G	Н	J	K	L	М
2027	N	Р	Q	R	S	Т	U	V	W	Х	Υ	Z
2028	а	b	С	d	е	f	g	h	i	j	k	m
2029	n	р	q	r	s	t	u	٧	W	х	у	Z

Reel Dimensions (mm):





Tape Dimensions (mm):

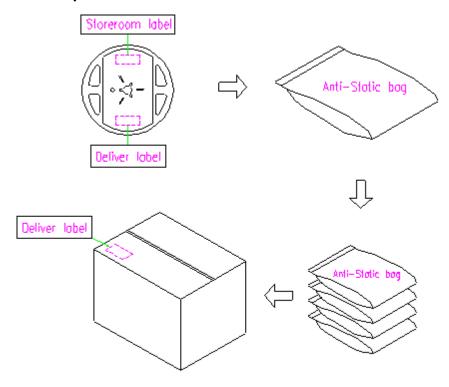


[NOTE]:

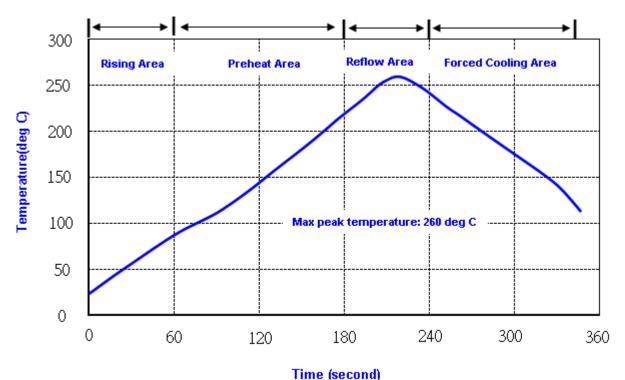
- 1. Unless otherwise specified tolerance on dimension +/-0.1 mm.
- 2. Material: conductive polystyrene with color black.
- 3. 10 pitch cumulative tolerance +/-0.2 mm.

Packing Quantity/Packing:

3K pcs maximum per reel



Reflow Profile:



Note: 1.Max peak temperature: 260+/-5 deg C; Time: 10+/-2 sec

2. Temperature: 217+/-5 deg C; Time: 90~100 sec

Reliability Specifications

Test name	Test process / method	Reference standard				
Mechanical characteristics						
resistance to Soldering heat (IR reflow)	Temp./ Duration:265°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701 -300(301)M(II)				
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 2000 Hz Sweep period : 20 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202G method 204				
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202G method 213				
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	J-STD-002				
Environmental	characteristics					
Thermal Shock	Heat cycle conditions -40 °C (30min) ←→ 85 °C (30min) * cycle time : 10 times	MIL-STD 883G method 1010.8				
Humidity test	Temperature : 85 ± 2 °C Relative humidity : 85% Duration : 96 hours	MIL-STD 202G method 103				
Dry heat (Aging test)	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 202G method 108A				
Cold resistance (Low Temp Storage)	Temperature : -40 ± 2 °C Duration : 96 hours	IEC 60068-2-1				

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

- 1. The design, manufacturing process, and specifications of this device are subject to change. 2. US or International patents may apply.
- 3. RoHS compliant from the first date of manufacture.